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# FXLP34

## Single Bit Uni-Directional Translator

### Features

- 1.0V to 3.6V  $V_{CC}$  Supply Voltage
- Converts Any Voltage (1.0V to 3.6V) to (1.0V to 3.6V)
- 4.6V Tolerant Inputs and Outputs
- $t_{PD}$ :  
- 4ns Typical for 3.0V to 3.6V  $V_{CC}$
- Power-Off High Impedance Inputs and Outputs
- Static Drive ( $I_{OH}/I_{OL}$ ):  
-  $\pm 2.6mA$  at 3.00V  $V_{CC}$
- Uses Proprietary Quiet Series™ Noise / EMI Reduction Circuitry
- Ultra-Small Micropak™ Leadless Packages
- Ultra-Low Dynamic Power

### Description

The FXLP34 is a single translator with two separate supply voltages:  $V_{CC1}$  for input translation voltages and  $V_{CC}$  for output translation voltages. The FXLP34 is part of Fairchild's Ultra Low Power (ULP) series of products. This device operates with  $V_{CC}$  values from 1.0V to 3.6V, and is intended for use in portable applications that require ultra low power consumption.

The internal circuit is composed of a minimum of buffer stages, to enable ultra low dynamic power.

The FXLP34 is uniquely designed for optimized power and speed, and is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

### Ordering Information

Part Number	Top Mark	Package	Packing Method
FXLP34P5X	X34	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3000 Units on Tape & Reel
FXLP34L6X	X3	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
FXLP34FHX	X3	6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

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## Pin Configuration

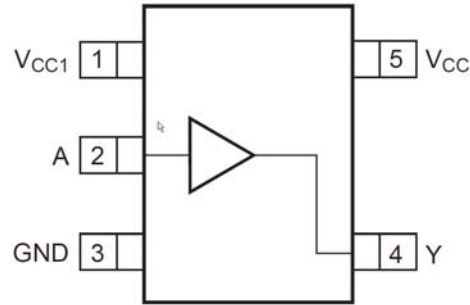


Figure 1. SC70 (Top View)

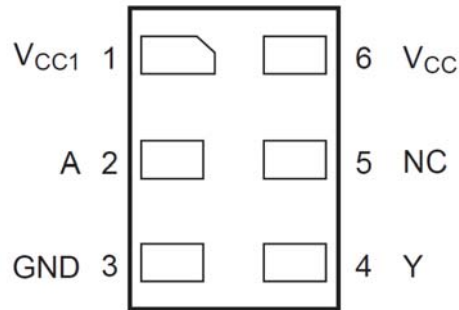


Figure 2. MicroPak™ (Top Through View)

## Pin Definitions

Pin # SC70	Pin # MicroPak™	Name	Description
1	1	V <sub>CC1</sub>	Input Translation Voltage
2	2	A	Input
3	3	GND	Ground
4	4	Y	Output
	5	NC	No Connect
5	6	V <sub>CC</sub>	Output Translation Voltage

## Truth Table

Inputs	Outputs
A	Y
L	L
H	H

H = Logic Level HIGH

L = Logic Level Low

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
$V_{CC}, V_{CC1}$	Supply Voltage		-0.5	+4.6	V
$V_{IN}$	DC Input Voltage		-0.5	+4.6	V
$V_{OUT}$	DC Output Voltage	HIGH or LOW State <sup>(1)</sup>	-0.5	$V_{CC} + 0.5V$	V
		$V_{CC}=0V$	-0.5	+4.6	
$I_{IK}$	DC Input Diode Current	$V_{IN} < 0$		-50	mA
$I_{OK}$	DC Output Diode Current	$V_{OUT} < 0V$		-50	mA
		$V_{OUT} > V_{CC}$		+50	
$I_{OH}/I_{OL}$	DC Output Source/Sink Current			±50	mA
$I_{CC}$ or $I_{GND}$	DC $V_{CC}$ or Ground Current per Supply Pin			±100	mA
$T_{STG}$	Storage Temperature Range		-65	150	°C
$P_D$	Power Dissipation at +85°C	SC70-6		180	mW
		MicroPak™-6		130	
		MicroPak2™-6		120	
ESD	Human Body Model, JEDEC:JESD22-A114			4000	V
	Charge Device Model, JEDEC:JESD22-C101			2000	

### Note:

- $I_O$  Absolute Maximum Rating must be observed.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
$V_{CC}, V_{CC1}$	Supply Voltage		1.0	3.6	V
$V_{IN}$	Input Voltage		0	3.6	V
$V_{OUT}$	Output Voltage	HIGH or LOW State	0	$V_{CC}$	V
		$V_{CC}=0V$	0	3.6	
$I_{OH}/I_{OL}$	Output Current in $I_{OH}/I_{OL}$	$V_{CC}=3.0$ to $3.6V$		±2.6	mA
		$V_{CC}=2.3$ to $2.7V$		±2.1	
		$V_{CC}=1.65$ to $1.95V$		±1.5	
		$V_{CC}=1.40$ to $1.60V$		±1.0	
		$V_{CC}=1.10$ to $1.30V$		±0.5	
		$V_{CC}=1.0V$		±20	µA
$T_A$	Operating Temperature, Free Air		-40	+85	°C
$\theta_{JA}$	Thermal Resistance	SC70-6		425	°C/W
		MicroPak™-6		500	
		MicroPak2™-6		560	

### Note:

- Unused inputs must be held HIGH or LOW. They may not float.

### Electrical Characteristics

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	V <sub>CC1</sub> (V)	T <sub>A</sub> =+25°C		T <sub>A</sub> =-40 to +85°C		Unit	
					Min.	Max.	Min.	Max.		
V <sub>IH</sub>	HIGH Level Input (V <sub>CC1</sub> )		1.0 to 3.6	1.0	0.65 x V <sub>CC1</sub>		0.65 x V <sub>CC1</sub>		V	
				1.10 ≤ V <sub>CC1</sub> ≤ 1.30	0.65 x V <sub>CC1</sub>		0.65 x V <sub>CC1</sub>			
				1.40 ≤ V <sub>CC1</sub> ≤ 1.60	0.65 x V <sub>CC1</sub>		0.65 x V <sub>CC1</sub>			
				1.65 ≤ V <sub>CC1</sub> ≤ 1.95	0.65 x V <sub>CC1</sub>		0.65 x V <sub>CC1</sub>			
				2.30 ≤ V <sub>CC1</sub> ≤ 2.70	1.6		1.6			
3.00 ≤ V <sub>CC1</sub> ≤ 3.60	2.1		2.1							
V <sub>IL</sub>	LOW Level Input		1.0 to 3.6	1.0		0.35 x V <sub>CC1</sub>		0.35 x V <sub>CC1</sub>	V	
				1.10 ≤ V <sub>CC1</sub> ≤ 1.30		0.35 x V <sub>CC1</sub>		0.35 x V <sub>CC1</sub>		
				1.40 ≤ V <sub>CC1</sub> ≤ 1.60		0.35 x V <sub>CC1</sub>		0.35 x V <sub>CC1</sub>		
				1.65 ≤ V <sub>CC1</sub> ≤ 1.95		0.35 x V <sub>CC1</sub>		0.35 x V <sub>CC1</sub>		
				2.30 ≤ V <sub>CC1</sub> ≤ 2.70		0.7		0.7		
3.00 ≤ V <sub>CC1</sub> ≤ 3.60		0.9		0.9						
V <sub>OH</sub>	HIGH Level Output (V <sub>CC</sub> )	I <sub>OH</sub> =-20μA	1.0	1.0 to 3.6	V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1		V	
			1.10 ≤ V <sub>CC1</sub> ≤ 1.30		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
			1.40 ≤ V <sub>CC1</sub> ≤ 1.60		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
			1.65 ≤ V <sub>CC1</sub> ≤ 1.95		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
			2.30 ≤ V <sub>CC1</sub> ≤ 2.70		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
			3.00 ≤ V <sub>CC1</sub> ≤ 3.60		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
		I <sub>OH</sub> =-0.5mA	1.10 ≤ V <sub>CC1</sub> ≤ 1.30	1.0 to 3.6	0.75 x V <sub>CC</sub>		0.70 x V <sub>CC</sub>			
		I <sub>OH</sub> =-1.0mA	1.40 ≤ V <sub>CC1</sub> ≤ 1.60		1.07		0.99			
		I <sub>OH</sub> =-1.5mA	1.65 ≤ V <sub>CC1</sub> ≤ 1.95		1.24		1.22			
		I <sub>OH</sub> =-2.1mA	2.30 ≤ V <sub>CC1</sub> ≤ 2.70		1.95		1.87			
I <sub>OH</sub> =-2.6mA	3.00 ≤ V <sub>CC1</sub> ≤ 3.60		2.61		2.55					
V <sub>OL</sub>	LOW Level Output	I <sub>OL</sub> =20μA	1.0	1.0 to 3.6			0.1		V	
			1.10 ≤ V <sub>CC1</sub> ≤ 1.30				0.1			0.1
			1.40 ≤ V <sub>CC1</sub> ≤ 1.60				0.1			0.1
			1.65 ≤ V <sub>CC1</sub> ≤ 1.95				0.1			0.1
			2.30 ≤ V <sub>CC1</sub> ≤ 2.70				0.1			0.1
		I <sub>OL</sub> =0.5mA	1.10 ≤ V <sub>CC1</sub> ≤ 1.30	1.0 to 3.6			0.30 x V <sub>CC</sub>			0.30 x V <sub>CC</sub>
		I <sub>OL</sub> =1.0mA	1.40 ≤ V <sub>CC1</sub> ≤ 1.60				0.31			0.37
		I <sub>OL</sub> =1.5mA	1.65 ≤ V <sub>CC1</sub> ≤ 1.95				0.31			0.35
		I <sub>OL</sub> =2.1mA	2.30 ≤ V <sub>CC1</sub> ≤ 2.70				0.31			0.33
		I <sub>OL</sub> =2.6mA	3.00 ≤ V <sub>CC1</sub> ≤ 3.60				0.31			0.33
I <sub>IN</sub>	Input Leakage Current	0 ≤ V <sub>IN</sub> ≤ 3.60		1.0 to 3.6			±0.1		±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	0 ≤ (V <sub>IN</sub> , V <sub>O</sub> ) ≤ 3.60	0	0			1.0		5.0	μA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	1.0 to 3.6	1.0 to 3.6			0.9		5.0	μA

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### AC Electrical Characteristics

Symbol	Parameter	Condition	V <sub>CC1</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.0	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		26.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	15.0	25.0	38.1	12.0			43.3
			1.40 to 1.60	14.0	24.0	36.7	11.0			42.0
			1.65 to 1.95	13.0	23.0	36.0	10.0			41.4
			2.30 to 2.70	12.0	22.0	35.5	9.0			40.9
			3.00 to 3.60	11.0	21.0	35.5	8.0			40.6
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.2	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		18.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	8.0	15.0	23.2	6.0			41.0
			1.40 to 1.60	7.5	14.0	21.7	5.5			39.1
			1.65 to 1.95	7.0	13.0	20.9	5.0			32.3
			2.30 to 2.70	6.5	12.0	20.4	4.5			29.6
			3.00 to 3.60	6.0	12.0	20.2	4.0			29.4
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.5	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		14.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	5.0	11.0	16.3	4.0			20.6
			1.40 to 1.60	4.8	10.0	14.8	3.5			19.3
			1.65 to 1.95	4.5	9.0	14.1	3.0			18.7
			2.30 to 2.70	4.0	8.0	13.5	2.5			18.0
			3.00 to 3.60	3.5	8.0	13.3	2.0			17.8
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.8	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		13.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	4.0	9.0	13.5	3.0			17.5
			1.40 to 1.60	3.5	8.0	12.0	2.5			16.3
			1.65 to 1.95	3.0	7.0	11.3	2.0			15.6
			2.30 to 2.70	2.5	6.0	10.7	1.5			15.0
			3.00 to 3.60	2.5	6.0	10.5	1.0			14.7
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=2.5	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		12.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	3.0	7.0	10.9	2.5			14.3
			1.40 to 1.60	2.5	6.0	9.4	2.0			13.1
			1.65 to 1.95	2.0	5.0	8.6	1.5			11.4
			2.30 to 2.70	1.5	4.0	8.0	1.0			10.8
			3.00 to 3.60	1.5	4.0	7.8	1.0			10.5
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=3.3	C <sub>L</sub> =10pF, R <sub>L</sub> =1MΩ	1.0		11.0			ns	Figure 3, Figure 4	
			1.10 to 1.30	3.0	6.0	10.1	2.0			13.8
			1.40 to 1.60	2.5	5.0	8.2	1.5			10.5
			1.65 to 1.95	2.0	4.0	7.4	1.0			9.9
			2.30 to 2.70	1.0	3.0	6.8	1.0			9.2
			3.00 to 3.60	1.0	3.0	6.6	1.0			9.0

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**AC Electrical Characteristics (Continued)**

Symbol	Parameter	Condition	V <sub>CC1</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.0	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		28.0				ns	Figure 3, Figure 4
			1.10 to 1.30	16.0	27.0	43.0	12.0	44.8		
			1.40 to 1.60	15.0	26.0	41.6	11.0	43.6		
			1.65 to 1.95	14.0	25.0	40.9	10.0	47.9		
			2.30 to 2.70	13.0	24.0	40.5	9.0	47.5		
			3.00 to 3.60	12.0	23.0	40.4	8.0	41.4		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.2	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		19.0				ns	Figure 3, Figure 4
			1.10 to 1.30	9.0	16.0	24.6	8.0	43.1		
			1.40 to 1.60	8.5	15.0	23.1	7.5	42.2		
			1.65 to 1.95	8.0	14.0	22.4	7.0	31.4		
			2.30 to 2.70	7.5	13.0	21.8	6.5	30.7		
			3.00 to 3.60	7.0	13.0	21.6	6.0	30.5		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.5	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		15.0				ns	Figure 3, Figure 4
			1.10 to 1.30	6.0	12.0	17.2	5.5	21.5		
			1.40 to 1.60	5.8	11.0	15.7	5.0	20.3		
			1.65 to 1.95	5.5	10.0	14.9	4.5	19.6		
			2.30 to 2.70	5.0	9.0	14.3	4.0	18.9		
			3.00 to 3.60	4.5	.0	14.2	3.5	18.7		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.8	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		14.0				ns	Figure 3, Figure 4
			1.10 to 1.30	5.0	8.0	14.2	5.5	18.2		
			1.40 to 1.60	4.5	7.0	12.7	4.0	17.0		
			1.65 to 1.95	4.0	6.0	11.9	3.5	16.3		
			2.30 to 2.70	3.5	5.0	11.3	3.0	15.7		
			3.00 to 3.60	3.5	5.0	11.2	2.5	14.4		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=2.5	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		12.0				ns	Figure 3, Figure 4
			1.10 to 1.30	4.0	7.0	11.3	3.5	14.9		
			1.40 to 1.60	3.5	6.0	9.8	3.0	13.6		
			1.65 to 1.95	3.0	5.0	9.1	2.5	12.0		
			2.30 to 2.70	2.5	4.0	8.5	2.0	11.3		
			3.00 to 3.60	2.5	4.0	8.3	2.0	11.1		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=3.3	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ	1.0		11.0				ns	Figure 3, Figure 4
			1.10 to 1.30	3.0	6.0	10.5	2.0	14.2		
			1.40 to 1.60	2.5	5.0	8.6	1.5	11.0		
			1.65 to 1.95	2.0	4.0	7.8	1.0	10.3		
			2.30 to 2.70	1.5	3.0	7.2	1.0	9.7		
			3.00 to 3.60	1.5	3.0	7.0	1.0	9.4		

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### AC Electrical Characteristics (Continued)

Symbol	Parameter	Condition	V <sub>CC1</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.0	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		34.0				ns	Figure 3, Figure 4
			1.10 to 1.30	19.0	32.0	48.6	15.0	55.5		
			1.40 to 1.60	18.0	31.0	47.1	14.0	52.3		
			1.65 to 1.95	17.0	30.0	46.4	13.0	50.6		
			2.30 to 2.70	16.0	29.0	45.9	12.0	49.2		
			3.00 to 3.60	15.0	28.0	45.8	10.0	49.1		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.2	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		22.0				ns	Figure 3, Figure 4
			1.10 to 1.30	11.0	19.0	29.0	10.0	46.5		
			1.40 to 1.60	10.0	18.0	27.5	9.0	42.6		
			1.65 to 1.95	9.0	17.0	26.7	8.0	36.7		
			2.30 to 2.70	8.5	16.0	26.1	7.0	36.0		
			3.00 to 3.60	8.0	16.0	26.0	6.0	35.9		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.5	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		16.0				ns	Figure 3, Figure 4
			1.10 to 1.30	6.0	13.0	19.8	5.5	25.3		
			1.40 to 1.60	5.8	12.0	18.3	5.0	23.0		
			1.65 to 1.95	5.5	11.0	17.6	4.5	22.4		
			2.30 to 2.70	5.0	10.0	17.0	4.0	21.7		
			3.00 to 3.60	4.5	9.0	16.8	3.5	21.5		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=1.8	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		15.0				ns	Figure 3, Figure 4
			1.10 to 1.30	5.0	11.0	16.2	5.5	20.4		
			1.40 to 1.60	4.5	10.0	14.7	4.0	19.2		
			1.65 to 1.95	4.0	9.0	13.9	3.5	18.5		
			2.30 to 2.70	3.5	8.0	13.3	3.0	17.9		
			3.00 to 3.60	3.5	8.0	13.1	2.5	17.6		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=2.5	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		13.0				ns	Figure 3, Figure 4
			1.10 to 1.30	4.0	8.0	12.7	3.5	15.9		
			1.40 to 1.60	3.5	7.0	11.2	3.0	14.3		
			1.65 to 1.95	3.0	6.0	10.5	2.5	13.6		
			2.30 to 2.70	2.5	5.0	9.9	2.0	12.8		
			3.00 to 3.60	2.5	5.0	9.7	2.0	12.5		
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay Output Translation V <sub>CC</sub> (V)=3.3	C <sub>L</sub> =30pF, R <sub>L</sub> =1MΩ	1.0		12.0				ns	Figure 3, Figure 4
			1.10 to 1.30	3.0	8.0	11.7	2.0	15.0		
			1.40 to 1.60	2.5	7.0	9.8	1.5	12.2		
			1.65 to 1.95	2.0	6.0	8.9	1.0	11.5		
			2.30 to 2.70	1.5	5.0	8.3	1.0	10.7		
			3.00 to 3.60	1.5	5.0	8.1	1.0	10.4		

### Capacitance

Symbol	Parameter	Conditions	V <sub>CC</sub> / V <sub>CC1</sub> (V)	T <sub>A</sub> =+25°C	Units
				Typical	
C <sub>IN</sub>	Input Capacitance			2	pF
C <sub>I/O</sub>	Input/Output Capacitance			4	pF
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>I</sub> =0V or V <sub>CC1</sub> , f=10MHz, V <sub>CC</sub> / V <sub>CC1</sub> =3.6V	1.0 to 3.60	8	pF



## Translator Power-up Sequence Recommendations

To ensure that the system does not experience unnecessary  $I_{CC}$  current draw, bus contention, or oscillations during power-up; adhere to the following guidelines. This device is designed with the output pin(s) supplied by  $V_{CC}$  and the input pin(s) supplied by  $V_{CC1}$ . The first recommendation is to begin by powering up the input side of the device with  $V_{CC1}$ . The Input pin(s) should be ramped with or ahead of  $V_{CC1}$  or held LOW. This guards against bus contentions and oscillations as

all inputs and the input  $V_{CC1}$  are powered at the same time. The output  $V_{CC}$  can then be powered to the target voltage level to which the device will translate. The output pin(s) then translate to logic levels dictated by the output  $V_{CC}$  levels.

Upon completion of these steps, the device can be configured for the desired operation. Following these steps helps prevent possible damage to the translator device as well as other system components.

## AC Loadings and Waveforms

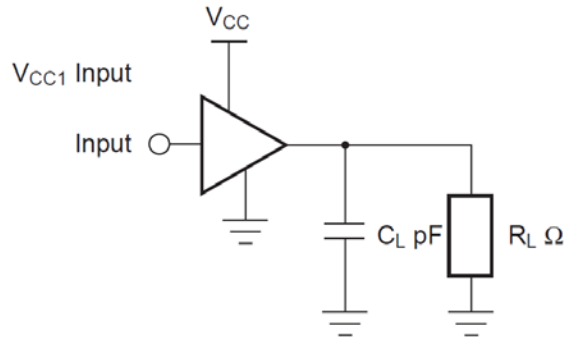


Figure 3. AC Test Circuit

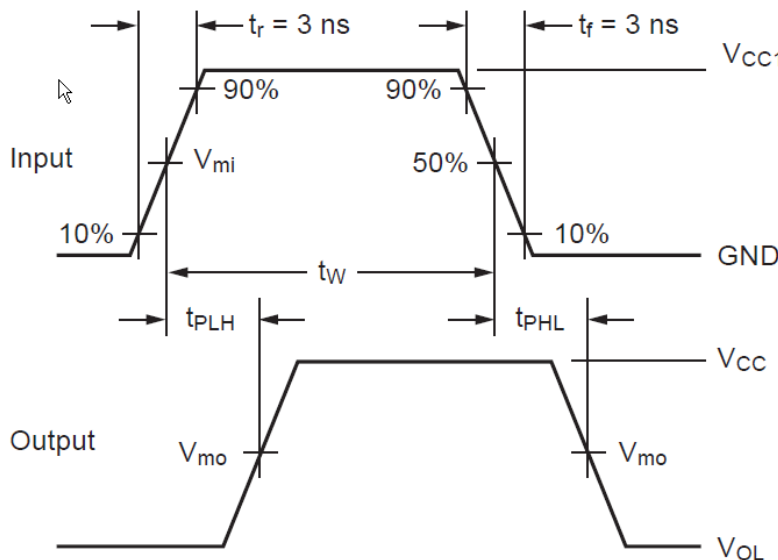
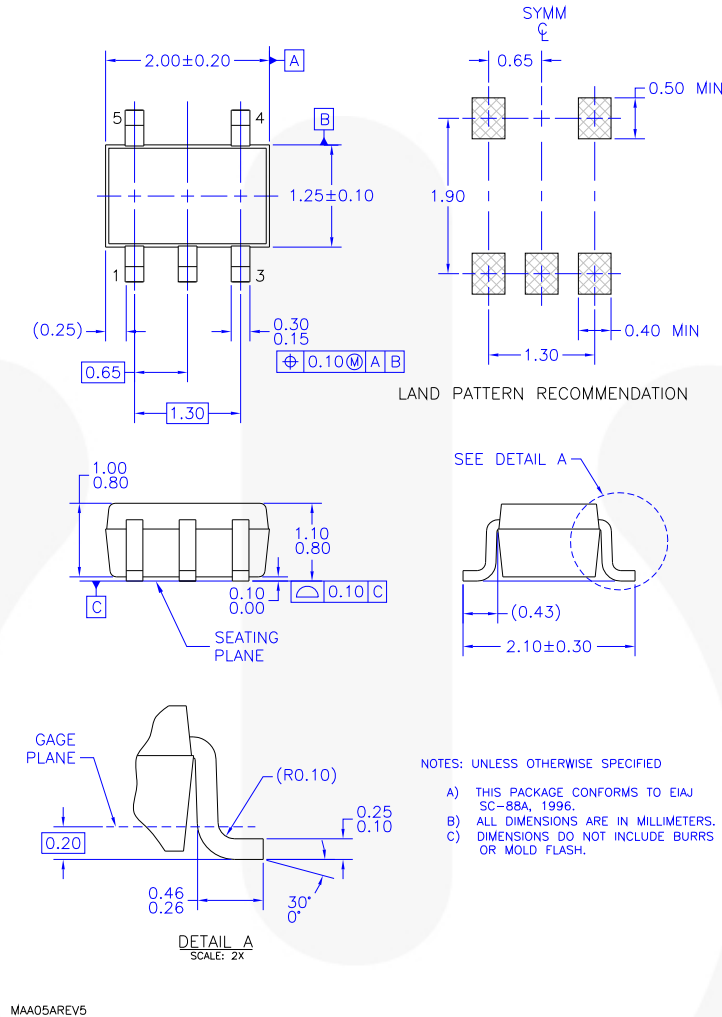


Figure 4. Waveform for Inverting and Non-Inverting Functions

Table 1. AC Load Table

Symbol	$V_{CC}$					
	3.3V $\pm$ 0.3V	2.5V $\pm$ 0.2V	1.8V $\pm$ 0.15V	1.5V $\pm$ 0.10V	1.2V $\pm$ 0.10V	1.0V
$V_{mi}$	1.5V	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$
$V_{mo}$	1.5V	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$

## Physical Dimensions



**Figure 5. 5-Lead, SC70, EIAJ SC-88a, 1.25mm Wide**

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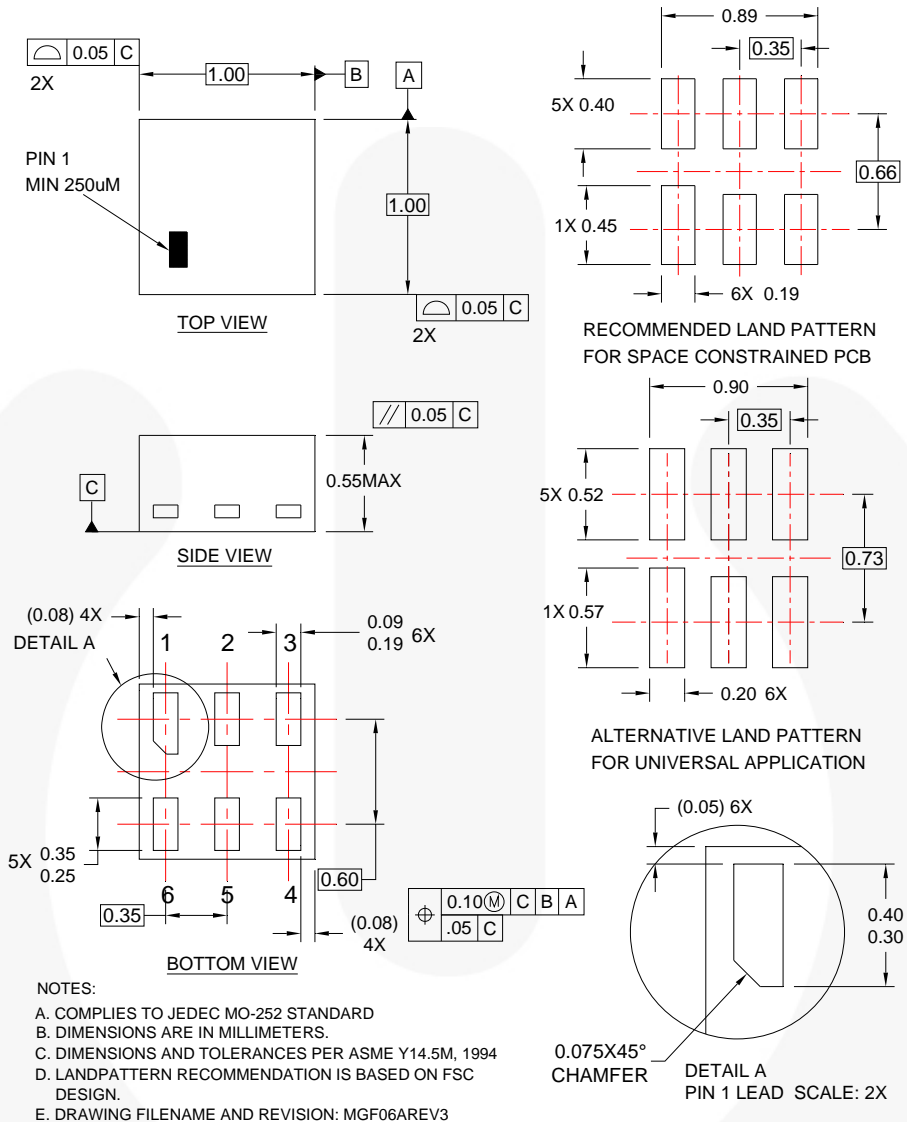
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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
P5X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



## Physical Dimensions



**Figure 7. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch**

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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
FHX	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



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| CorePLUS™                | Green FPST™ e-Series™  | QFET®                                | TinyBuck™                              |
| CorePOWER™               | Gmax™                  | QS™                                  | TinyCalc™                              |
| CROSSVOLT™               | GTO™                   | Quiet Series™                        | TinyLogic®                             |
| CTL™                     | IntelliMAX™            | RapidConfigure™                      | TINYOPTO™                              |
| Current Transfer Logic™  | ISOPLANAR™             | ™                                    | TinyPower™                             |
| DEUXPEED®                | MegaBuck™              | Saving our world, 1mW/WkW at a time™ | TinyPWM™                               |
| Dual Cool™               | MICROCOUPLER™          | SignalWise™                          | TinyWire™                              |
| EcoSPARK®                | MicroFET™              | SmartMax™                            | TnFault Detect™                        |
| EfficientMax™            | MicroPak™              | SMART START™                         | TRUECURRENT®*                          |
| ESBC™                    | MicroPak2™             | SPM®                                 | µSerDes™                               |
| <b>F</b> ®               | MillerDrive™           | STEALTH™                             | SerDes™                                |
| Fairchild®               | MotionMax™             | SuperFET®                            | UHC®                                   |
| Fairchild Semiconductor® | Motion-SPM™            | SuperSOT™-3                          | Ultra FRFET™                           |
| FACT Quiet Series™       | mWSaver™               | SuperSOT™-6                          | UniFET™                                |
| FACT®                    | OptoHiT™               | SuperSOT™-8                          | VCX™                                   |
| FAST®                    | OPTOLOGIC®             | SupreMOS®                            | VisualMax™                             |
| FastvCore™               | OPTOPLANAR®            | SynCFET™                             | XST™                                   |
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Rev. 153